AMENDMENTS TO THE SPECIFICATION

Please replace the two consecutive paragraphs beginning on page 6, line 7 and ending on page 6, line 19, with the following replacement paragraphs:

The outer edges 136a, 146a, **116a, 118a,** and **120a** **[[160a]]** of leads 106, 114, and 116, 118, and 120, respectively, are generally orthogonal and, in this embodiment, extend slightly beyond the tapered sidewalls 195 of encapsulant material 194. Typically, the outer edges 136a, 146a, **116a, 118a, and 120a** **[[160a]]** are formed by severing the leads from a leadframe, such as with a punch or saw.

The die 102, which may comprise a PMOSFET device, is mounted on the first surface 124 of the die pad 104. The die 102 includes opposing first and second surfaces 162 and 163, which may be substantially parallel to each other. The second surface 163 of the die 102 is mounted on the first surface 124 of the die pad 104 with metal solder, an electrically conductive die attach adhesive, or other conventional conductive die attach means. In one embodiment, the leads 116, 118, 120 are source leads in that **[[the]]** **they** are integrally coupled with die pad 104, which, in turn, is electrically coupled to the source terminal of a PMOSFET die 102.